



Material Composition Declaration

EPC2105

Company Name	Efficient Power Conversion (EPC)	Issue Date:	3/14/2018
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0283	Contact Email:	yanping.ma@epc-co.com
Part Weight:	23.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	19.9310	86.6459	89.2935	866459
	Silicon oxide	7631-86-9	0.0889	0.3866		3866
	Silicon nitride	12033-89-5	0.0323	0.1404		1404
	Gallium nitride	25617-97-4	0.1022	0.4441		4441
	Aluminum	7429-90-5	0.1603	0.6969		6969
	Aluminum nitride	24304-00-5	0.0248	0.1080		1080
	Titanium	7440-32-6	0.0038	0.0165		165
	Titanium nitride	25583-20-4	0.0132	0.0576		576
	Copper	7440-50-8	0.0053	0.0232		232
	Tungsten	7440-33-7	0.0051	0.0221		221
	Polyimide		0.1731	0.7523		7523
Under Bump Metal	Titanium	7440-32-6	0.0015	0.0065	0.5505	65
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.1251	0.5440		5440
Solder Bump	Tin	7440-31-5	2.2310	9.6990	10.1560	96990
	Silver	7440-22-4	0.0934	0.4062		4062
	Copper	7440-50-8	0.0117	0.0508		508
Sum in total:			23.0028	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.